

L Number	Hits	Search Text	DB	Time stamp
1	13361	(714/724,734,735,736,738,739,740,741,742,743 324/763,764,765,158.1).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 12:20
-	4	("6028439" "5323107").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:08
-	7	("023537").ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:01
-	2	("5793117").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:15
-	2	("6057679").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:42
-	4842	(probe adj card probe solder adj bump bond adj pad) and ATE IC near2 tester	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:44
-	898	((probe adj card probe solder adj bump bond adj pad) and ATE IC near2 tester) and (IC integrated adj circuit) and (microprocessor microcontroller processor controller)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:47
-	219	((((probe adj card probe solder adj bump bond adj pad) and ATE IC near2 tester) and (IC integrated adj circuit) and (microprocessor microcontroller processor controller)) and (DUT device-under-test)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/13 11:48
-	1		USPAT; US-PGPUB	2004/04/13 12:31